



Morphology and Electrochemistry Drive Corrosion of Electroless Nickel Immersion Gold Films: A Multi-Technique Analysis



PRESENTED BY

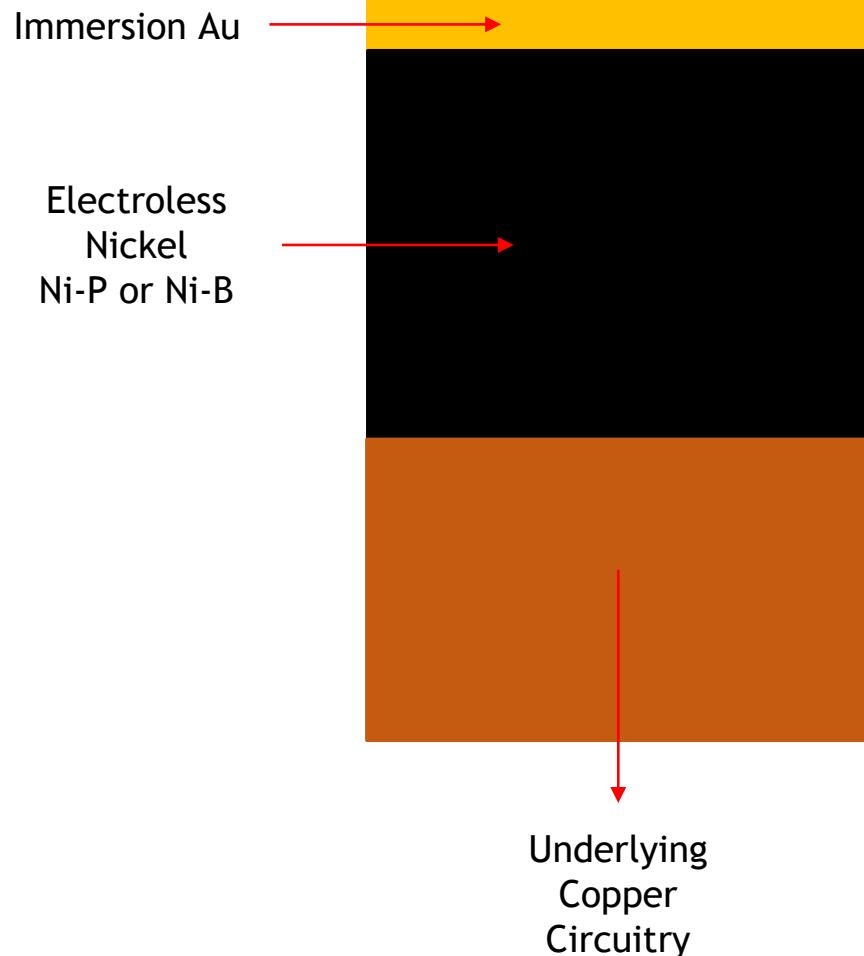
Elliott Fowler, Sandia National Labs (NM)

Team –

Samantha G. Rosenberg, Jessica Faubel, Melissa Meyerson (SNL), Rupesh Rajendran, Jahnavi Desai Choundraj, Josh Kacher, Preet Singh (Georgia Tech.)

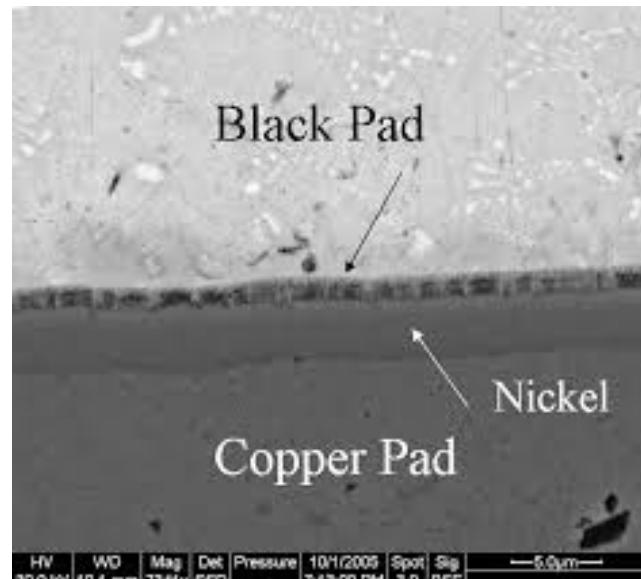
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Electroless Nickel Immersion Gold (ENIG)



Enhance solderability to copper pads

Minimize oxidation of base Cu layer

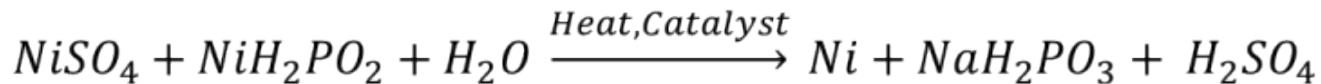


“Black Pad” phenomenology not well explained in literature

Pecht et al 2008
doi:10.1016/j.microrel.2008.02.003



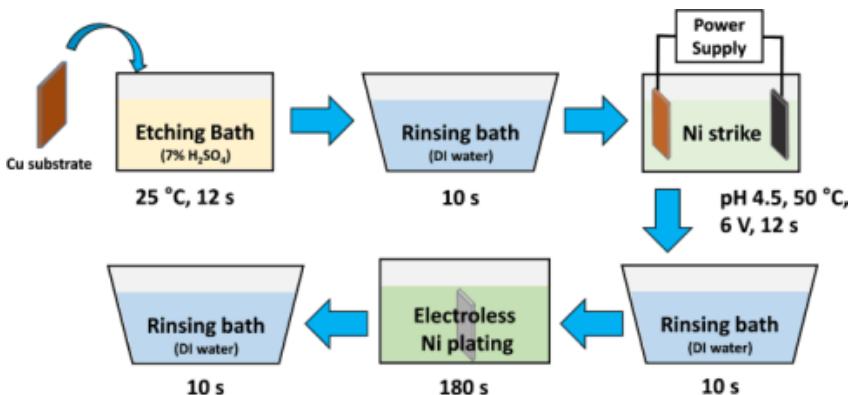
ENIG Plating Simplified



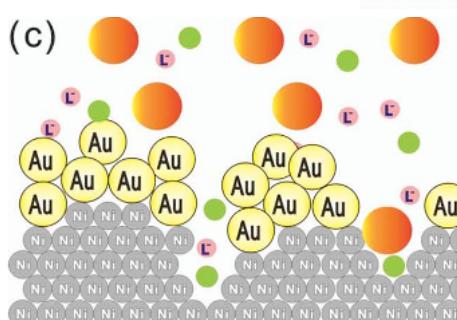
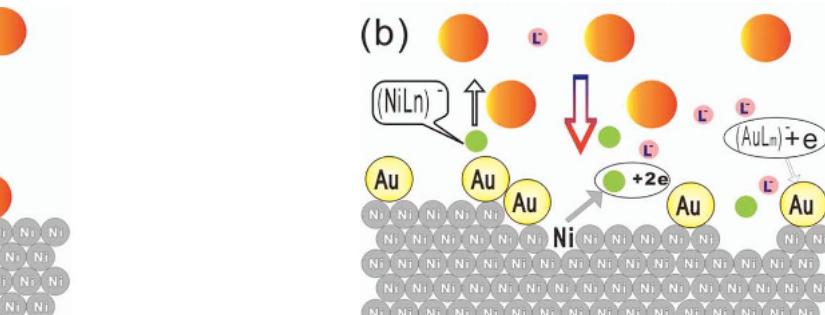
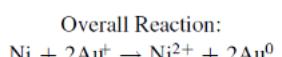
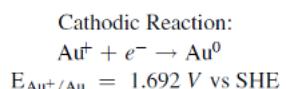
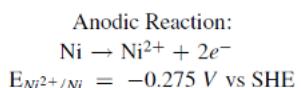
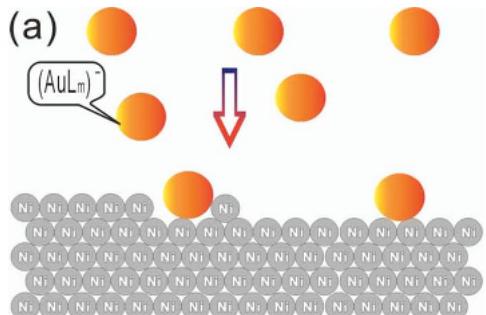
Process Inputs

1) Electroless Nickel

Metal salt concentration
 Additive 1 concentration
 Additive 2 concentration
 pH
 Temperature
 Current density
 Agitation



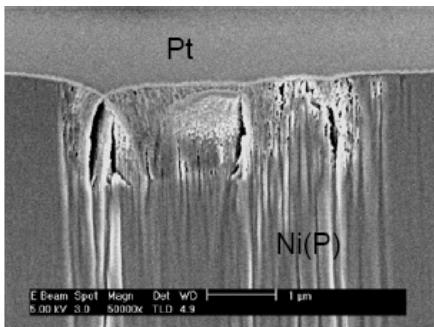
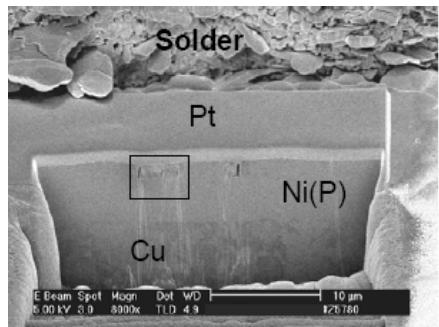
2) Immersion Gold



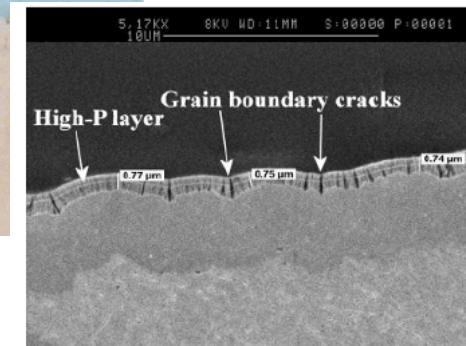
Liu *et al* 2007

<https://doi.org/10.1149/1.2790281>

Let's Agree to Disagree on the Root Cause(s)



Too Much (or Too Little) Phos.

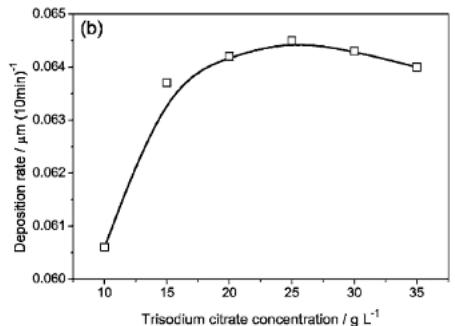
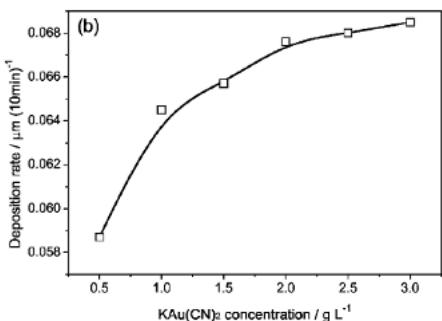


Galvanic Hyper-Corrosion of Ni(P)

Zeng *et al* 2006

<https://doi.org/10.1109/ITHERM.2006.1645469>

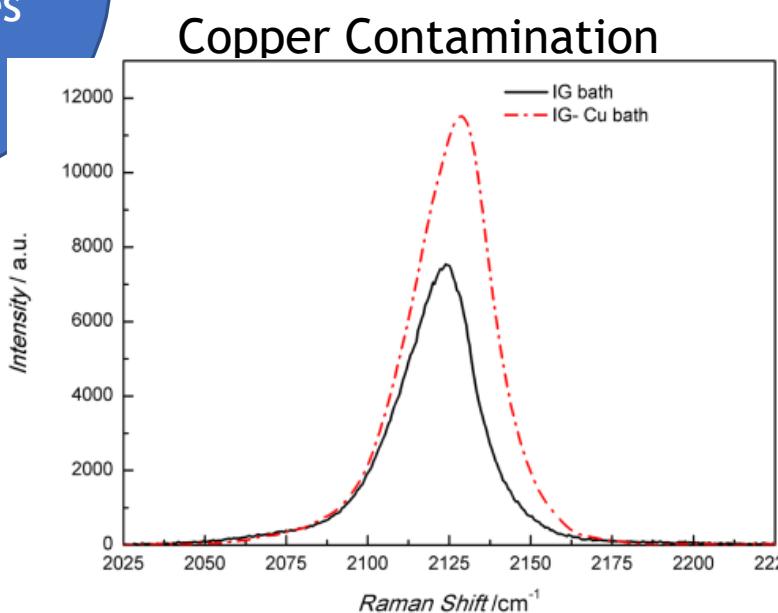
Potential Root Causes



Additives and Complexing Agents

Liu *et al* 2007

<https://doi.org/10.1149/1.2790281>

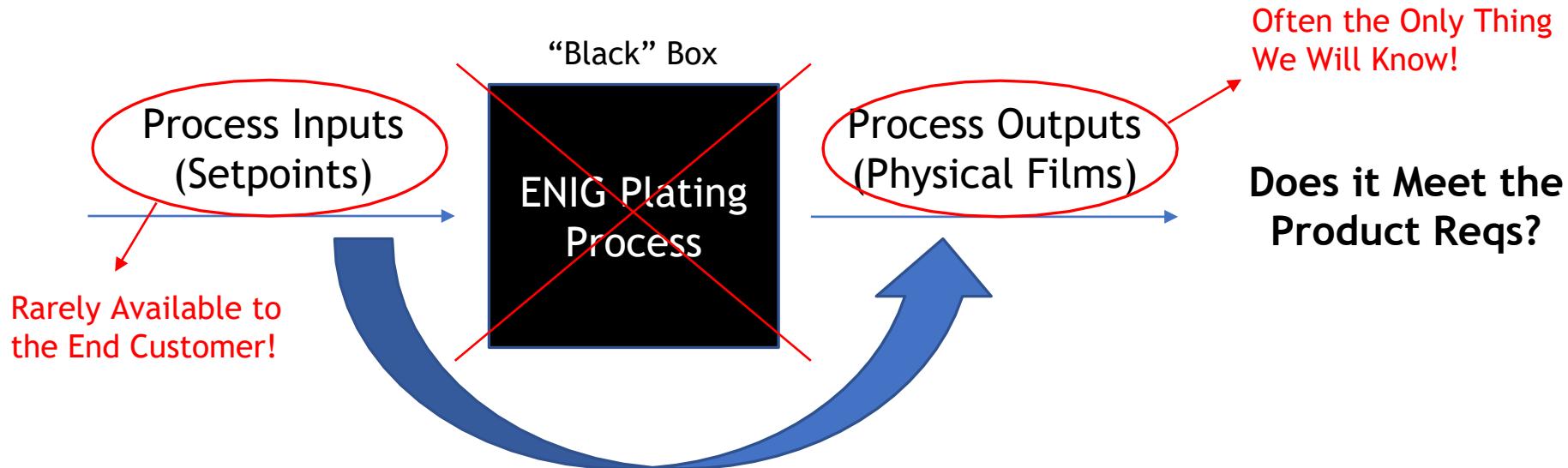


Accogli *et. al* 2022

<https://doi.org/10.1149/1945-7111/ab8ce6>



In-Situ Diagnosis of the Root Cause of Poor ENIG Plating is a High-Complexity, Low Reward Effort

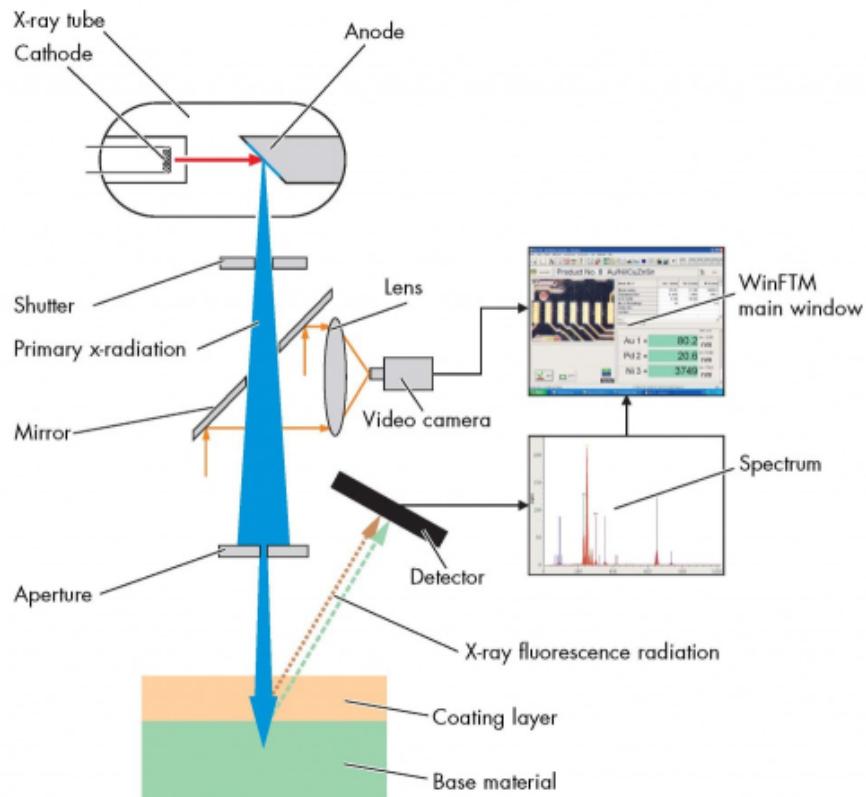


Can We Develop Methodologies to Distinguish Amongst These Potential Failure Modes Without the Luxury of Peeking Into the Black Box?



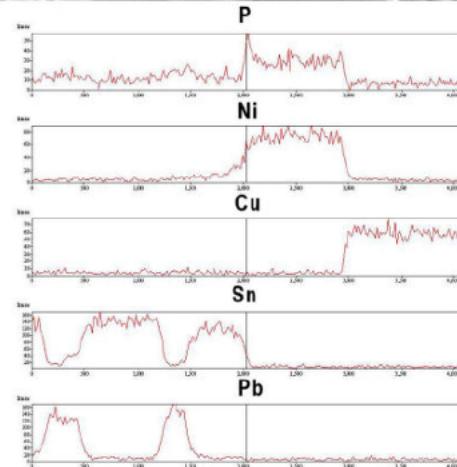
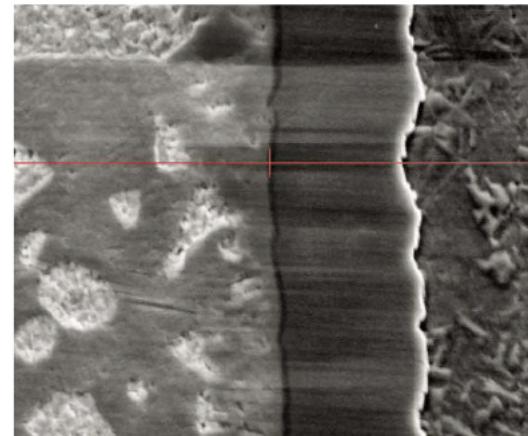
How is ENIG (Post)Characterized Now?

X-Ray Fluorescence (XRF) Spectroscopy



Chemical speciation, some structural information

FIB Section and SEM/EDS



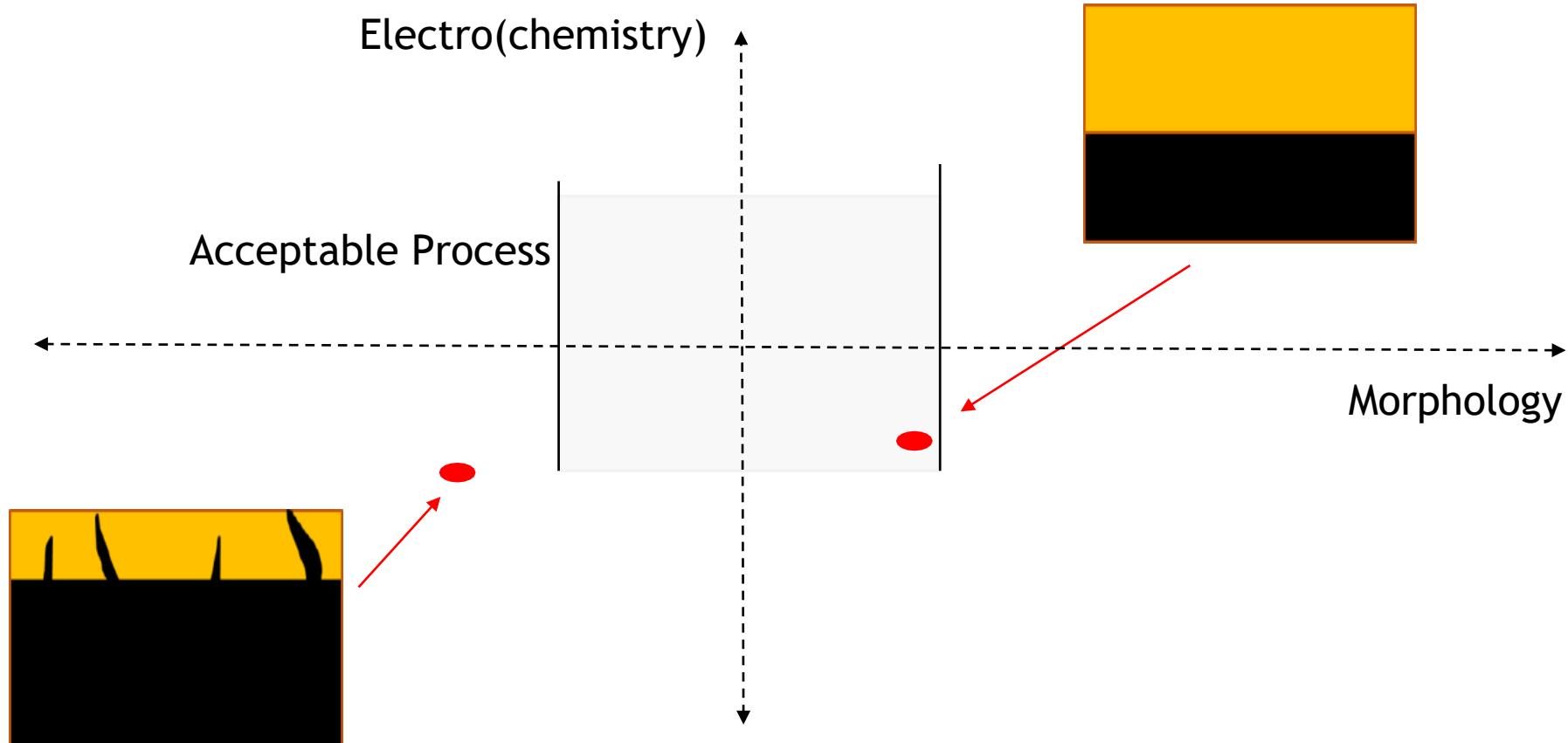
Low-quality chemical speciation, high-quality structural information

Electrochemical Information?

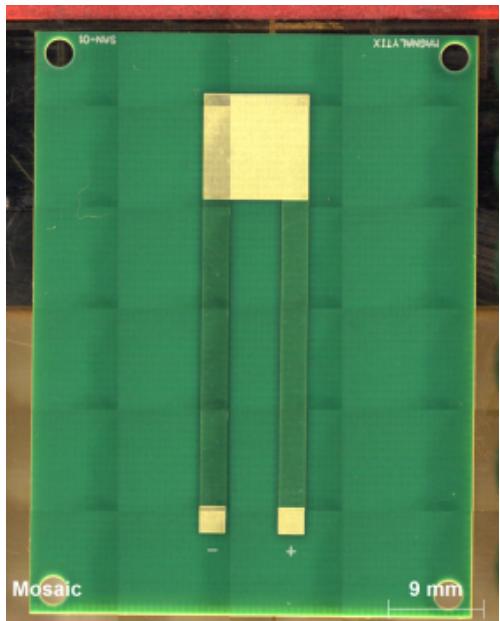


Hypothesis

Electro(chemistry) and Morphology Dictate Whether ENIG Films Meet Performance Requirements



Insights Into Both the Electro(chemistry) and Morphology of an ENIG Film Are Necessary to Properly Classify Whether Process -> Performance



Electro(chemistry)

Cyclic Polarization

Preet Singh
Georgia Tech.



SVET

XPS Depth Profiling

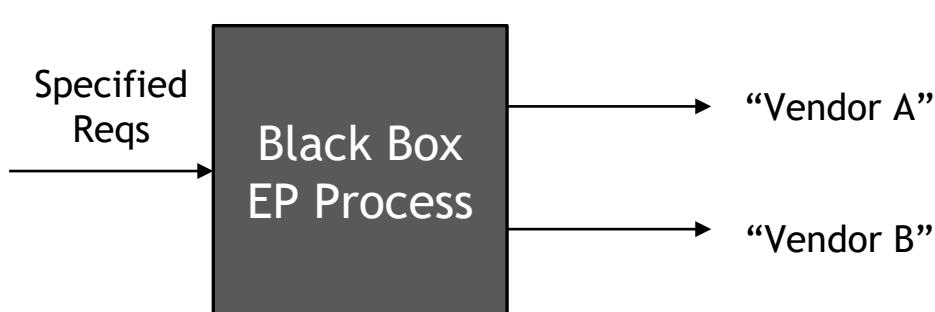
Samantha Rosenberg
Sandia Nat'l Labs



Morphology

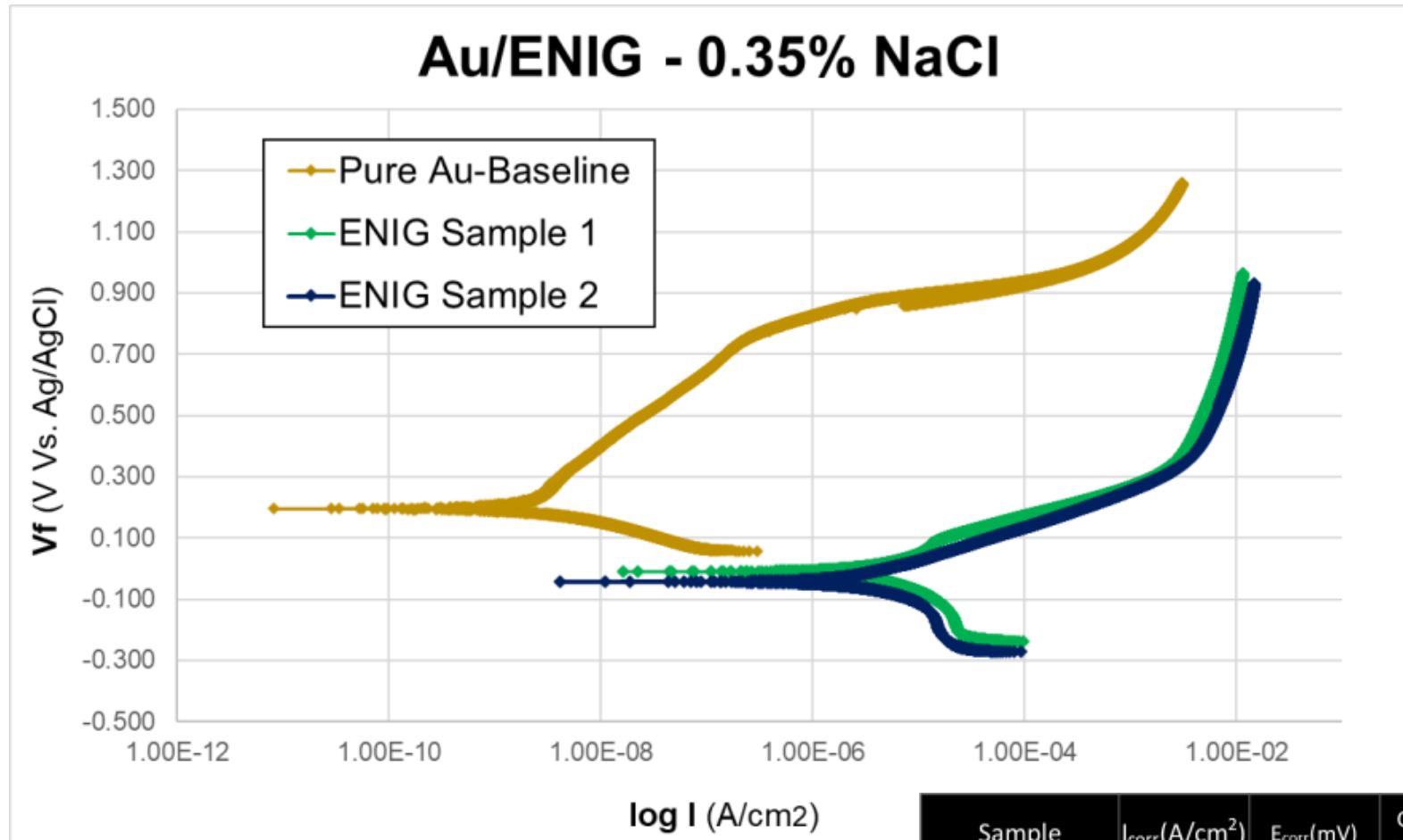
SEM/STEM

Josh Kacher
Georgia Tech.

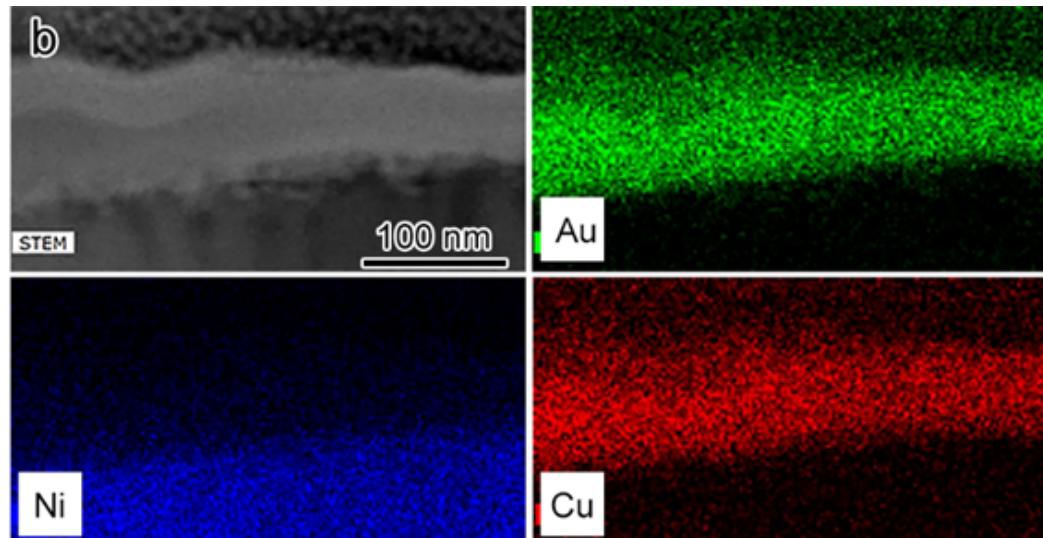
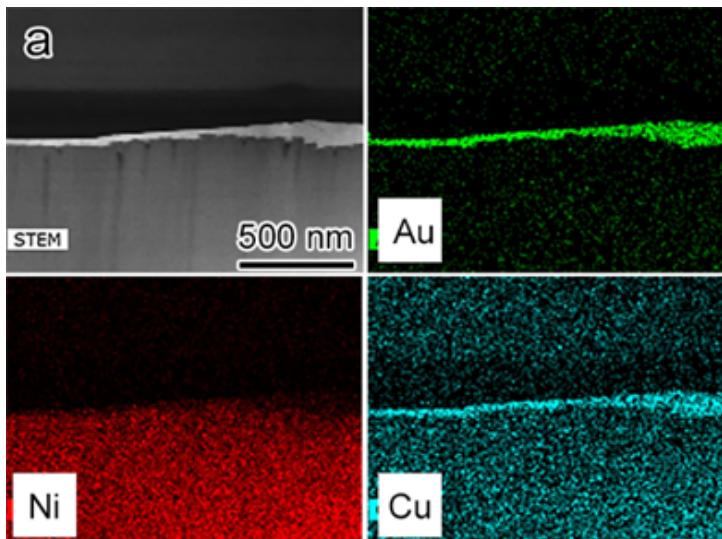




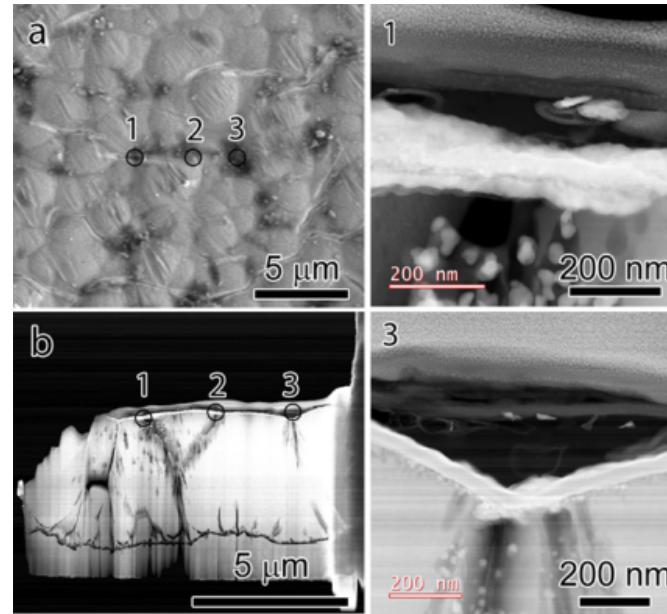
Results (Cyclic Polarization)



Results (Scanning/Transmission Electron Microscopies)



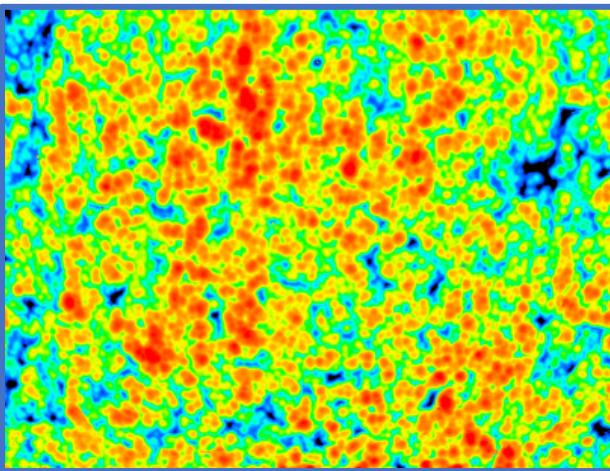
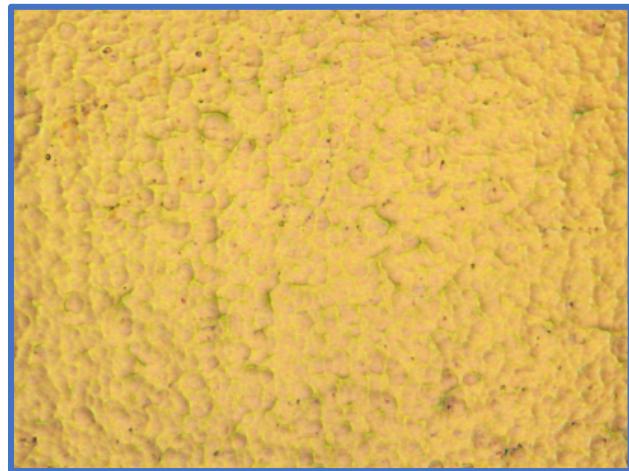
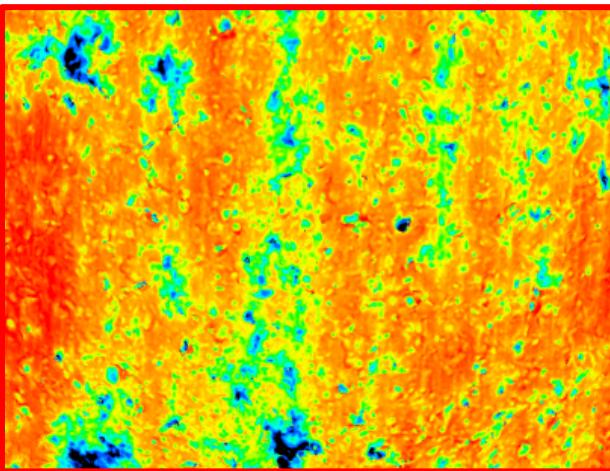
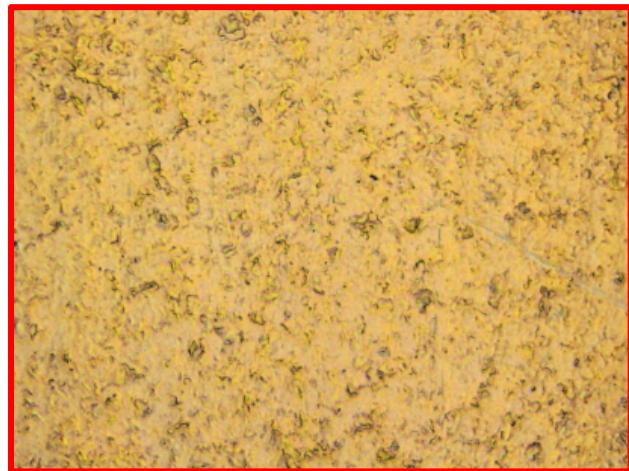
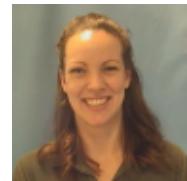
Was noted that one Vendor's samples appeared rougher than the other..



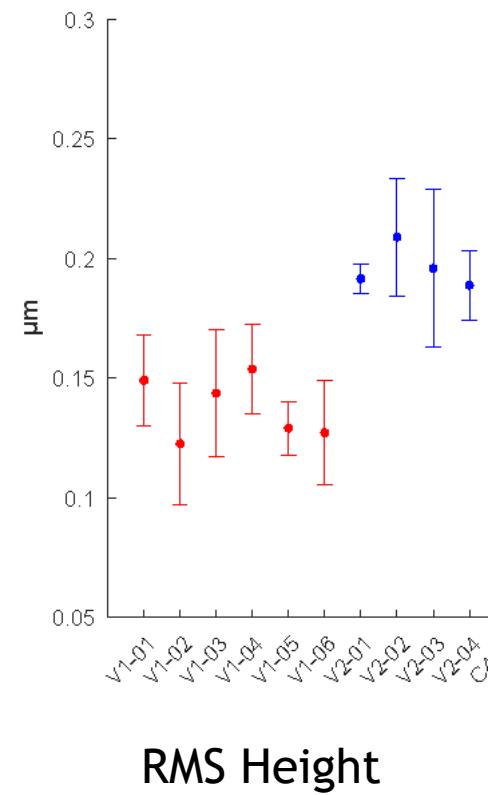
Aside - Surface Topology (Laser Scanning Confocal Microscopy)



Jessica Faubel
Sandia Nat'l Labs



← 272 μm →

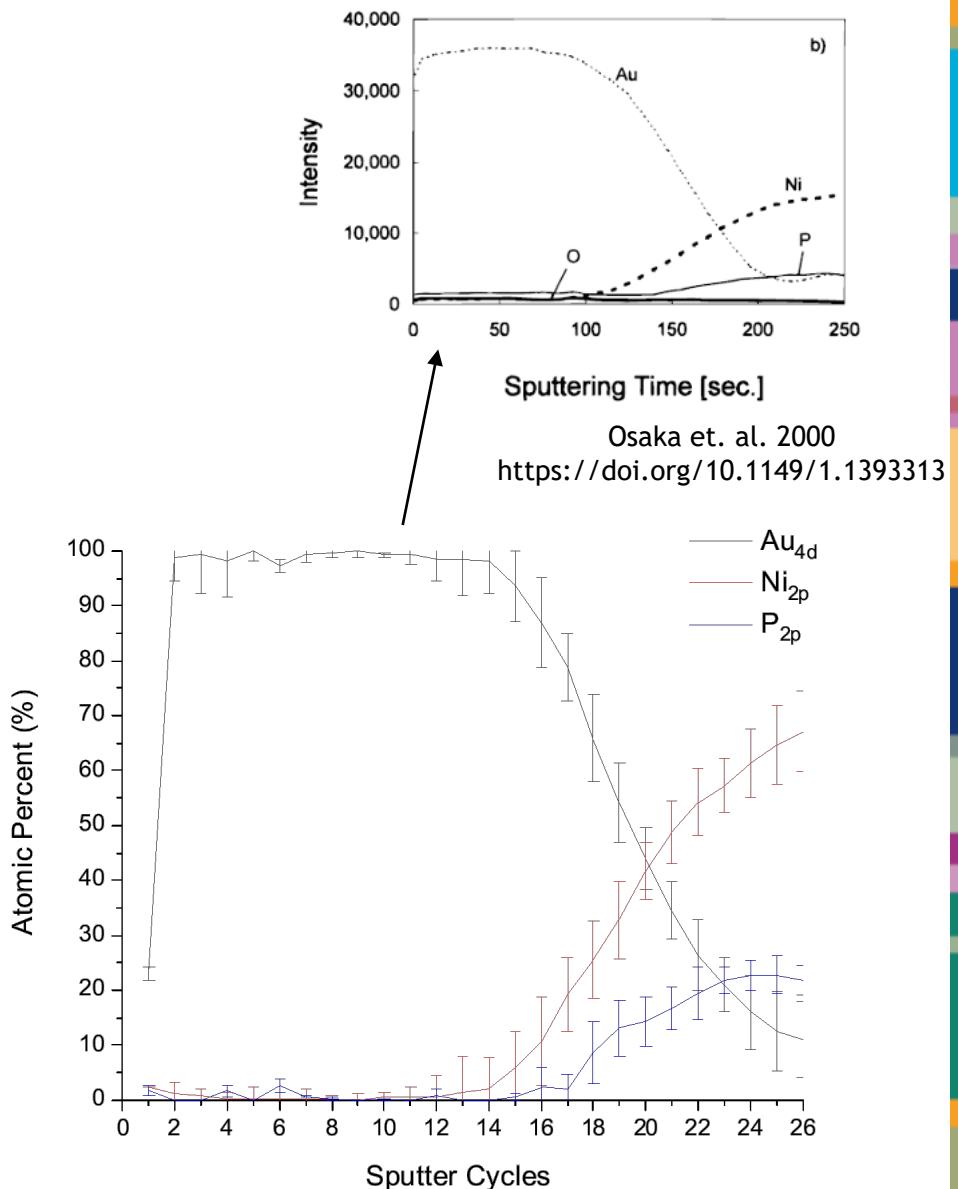
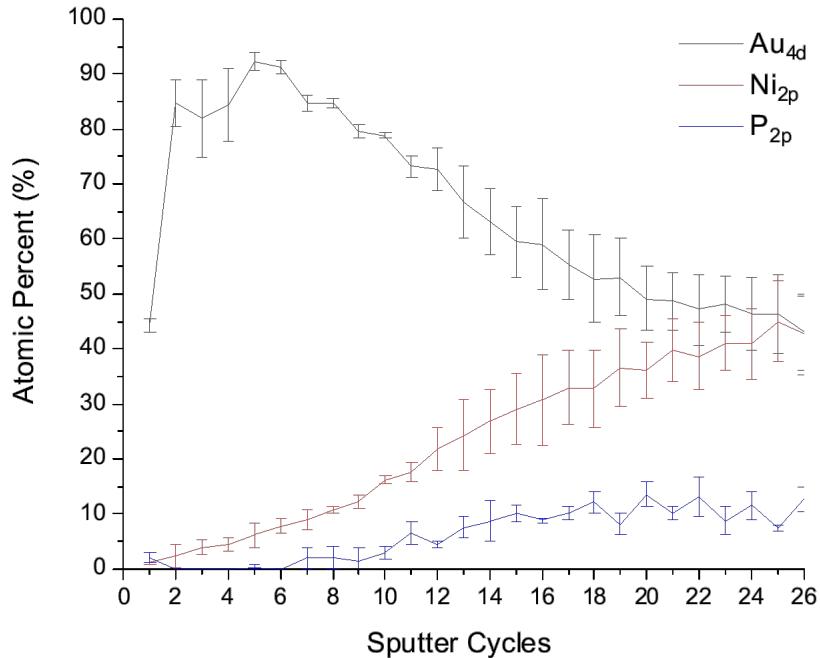


Results (X-Ray Photoelectron Spectroscopy)



Sample Identifier (Vendor, Spot, Sputter Cycle)	Au 4f %	C 1s %	Cu 2p %	Ni 2p %	O 1s %	P 2p %
Vendor A 1.1	37.88	42.53	3.01	1.26	13.86	1.46
Vendor A 1.2	82.62	10.06	2.56	2.46	2.30	0.00
Vendor A 2.1	50.73	28.21	5.23	0.84	12.40	2.60
Vendor A 2.2	86.63	6.81	2.81	2.24	1.51	0.00
Vendor B 1.1	23.35	48.44	0.56	2.47	24.19	1.00
Vendor B 1.2	98.36	0.00	0.00	1.64	0.00	0.00
Vendor B 2.1	22.71	50.70	0.45	2.38	21.55	2.23
Vendor B 2.2	99.47	0.00	0.00	0.53	0.00	0.00

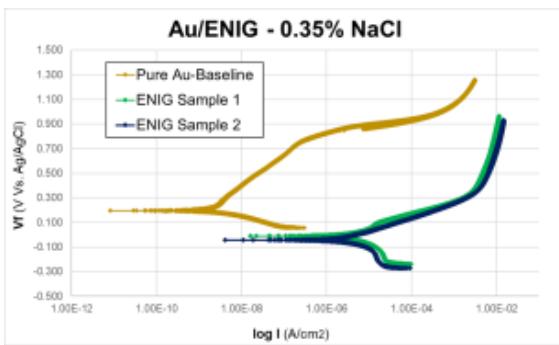
Results (X-Ray Photoelectron Spectroscopy Depth Profiling)



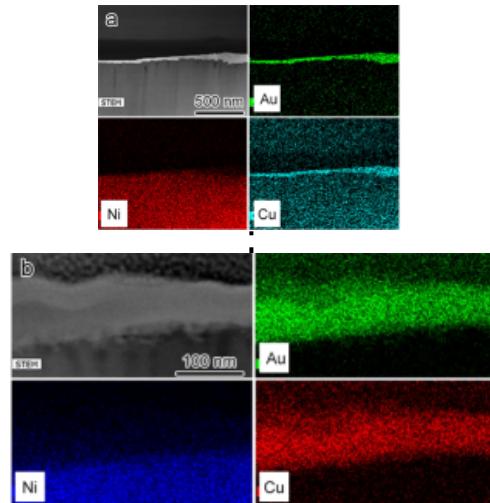


Putting It All Together

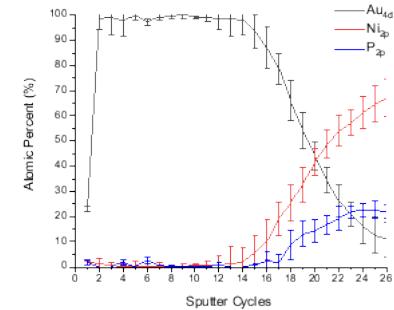
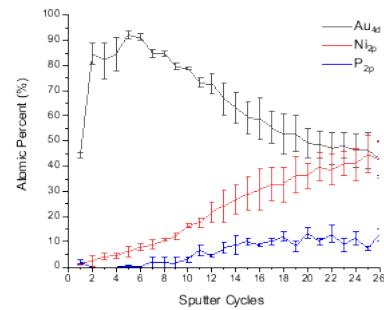
More Similar than Different



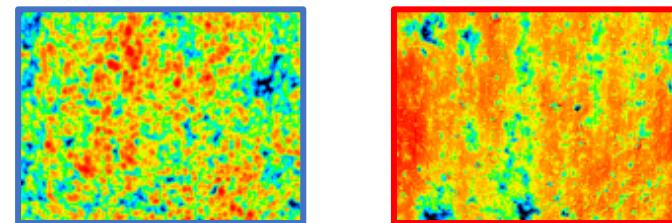
Vendor Samples Have Similar Passivity (or lack thereof)



More Different than Similar



Vendor Samples Have Clearly Different Heterogeneity / Porosity

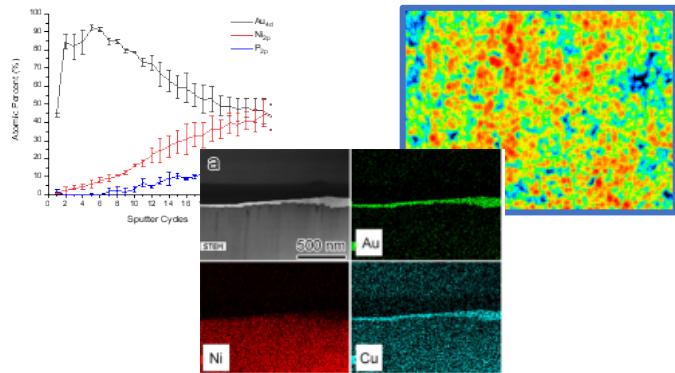


Vendor Samples Have Similar Morphological Defects and Contaminant Chemistry, Different Roughnesses

Putting It All Together

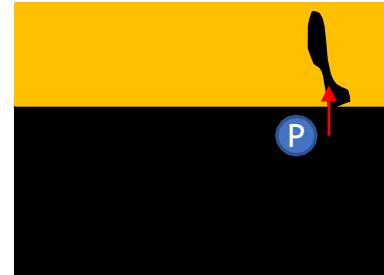
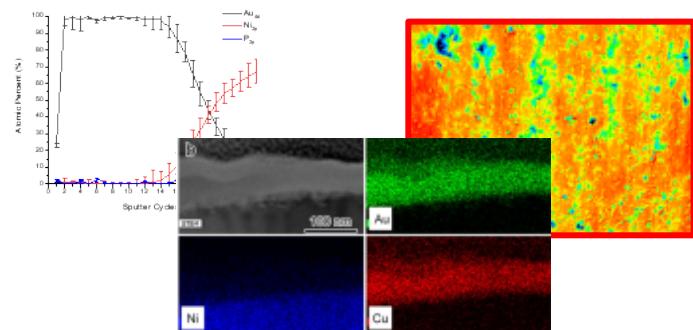


Vendor A



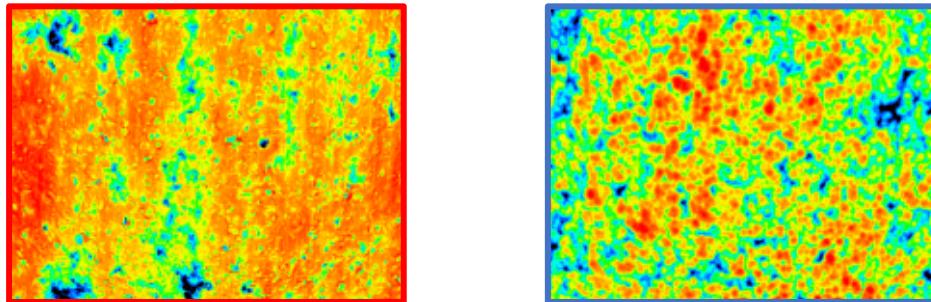
Poorly controlled plating conditions led to high Au porosity, susceptibility to Ni hyper corrosion in sol'n

Vendor B



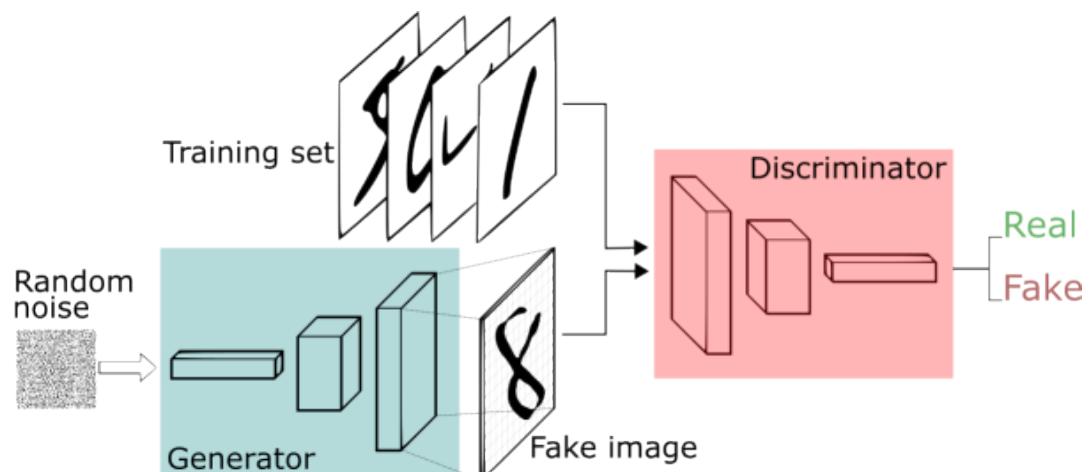
More ideal Au plating conditions, but choice of bath additives may have led to P-enrichment at Ni-Au interface, reducing film passivity

For classifying ‘good’ and ‘bad’... we need a much less comprehensive process



We can clearly see that the surface topology is encoding information about the SEM/TEM learned morphology, as well as the XPS learned ‘porosity’
 Electrochemistry is likewise implied by these properties since the layers are sequential and conformal

These latent ‘fingerprints’ of the process-structure-property relationships could allow us to predict performance based on a training set of well characterized samples



Questions?



Preet Singh



Josh Kacher



Rupesh Rajendran

Jahnavi Desai Choundraj

Samantha Rosenberg



Jessica Faubel



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Backup Slides



Results (Scanning Vibrating Electrode Technique)

